OPB822S, OPB822SD OPB826S, OPB826SD

Features:

- Non-contact switching
- Single or double apertures for high resolution
- · Choice of slot widths
- Choice of side-by-side or over/under dual channels
- Choice of electrical outputs



OPB822

Description:

Each **OPB822** and **OPB826** slotted switch consists of two infrared emitting diodes and two NPN silicon phototransistors mounted on opposite sides of a 0.090" (2.29 mm) wide slot **(OPB822)** or a 0.100" (2.54 mm) wide slot **(OPB826)**.

OPB822 uses an side-by-side mounting configuration, while **OPB826** uses an over/under mounting configuration. **OPB822S** has 0.01" by 0.04" (0.25 mm x 1.02 mm) apertures in front of both phototransistors while the **OPB822SD** has the aperture in front of both phototransistors and both emitters. The **OPB826S** has 0.04" by 0.04" (1.02 mm x 1.02 mm) apertures in front of both phototransistors while the **OPB826SD** has the aperture in front of both phototransistors and both emitters.

Dual channels enable direction of travel sensing, with the low-cost plastic housing reduces possible interference from ambient light and provides protection from dust and dirt.

Phototransistor switching occurs when an opaque object passes through the device slot.

For information on encoder design, see Application Bulletin 203 at:

Custom electrical, wire and cabling and connectors are available. Contact your local representative or OPTEK for more information.

Applications:

- Encoders
- Non-contact object sensing
- Assembly line automation
- Machine automation
- Equipment security
- Machine safety

Part Number	LED Peak Wavelength	Sensor	Slot Width / Depth	Aperture Emitter/ Sensor	Lead Length / Spacing
OPB822S	Dual	Dual	0.09" /	None / 0.01"	0.35" /
OPB822SD	935 nm	Transistor	0.30"	0.01" / 0.01"	0.30"
OPB826S	Dual	Dual	0.10" /	NA / 0.04"	0.20" /
OPB826SD	890 nm	Transistor	0.42"	0.04" / 0.04"	0.74"

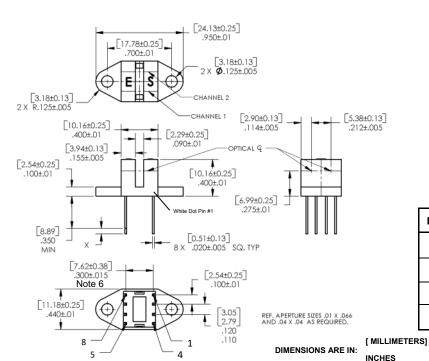


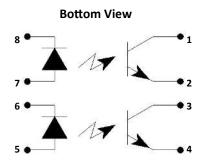
OPB822S, OPB822SD

OPB826S, OPB826SD



OPB822

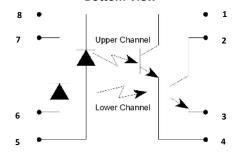




Pin #	Description	Pin #	Description
8	Cathode-1	1	Collector-1
7	Anode-1	2	Emitter-1
6	Cathode-2	3	Collector-2
5	Anode-2	4	Emitter-2

OPB826

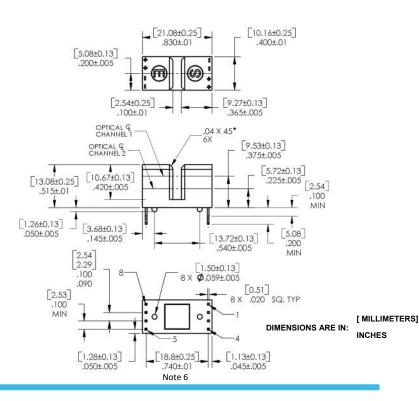
Bottom View



Pin #	Description	Pin #	Description
8	Cathode-1	1	Collector-1
7	Cathode-2	2	Collector-2
6	Anode-2	3	Emitter-2
5	Anode-1	4	Emitter-1

CONTAINS POLYSULFONE

To avoid stress cracking, we suggest using ND Industries' Vibra-Tite for thread-locking. Vibra-Tite evaporates fast without causing structural failure in OPTEK's molded plastics.



General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

OPB822S, OPB822SD

OPB826S, OPB826SD



Absolute Maximum Ratings (T_A = 25° C unless otherwise noted)

Storage & Operating Temperature Range	-40° C to +85° C
Lead Soldering Temperature [1/16 inch (1.6mm) from the case for 5 sec. with soldering iron] (1)	240°C

Input Diode

Forward DC Current	
OPB822S, OPB822SD	50 mA
OPB826S, OPB826SD	40 mA
Peak Forward Current (1 μs pulse width, 300 pps)	1 A
Reverse DC Voltage	2 V
Power Dissipation ⁽²⁾	100 mW

Output Phototransistor

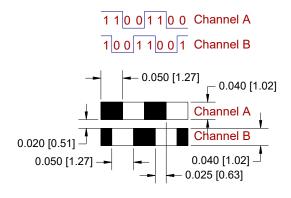
Collector-Emitter Voltage	30 V
Emitter-Collector Voltage	5 V
Collector DC Current	30 mA
Power Dissipation ⁽²⁾	100 mW

Notes:

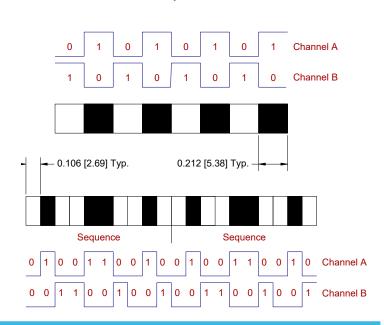
- (1) RMA flux is recommended. Duration can be extended to 10 seconds maximum when flow soldering.
- (2) Derate linearly 1.67 mW/°C above 25° C.
- (3) Methanol or isopropanol are recommended as cleaning agents. Plastic housing is soluble in chlorinated hydrocarbons and ketones. Spray and wipe; do not submerge.
- (4) Derate linearly 3.33 mW/°C above 25° C.
- (5) All parameters tested using pulse techniques.
- (6) Feature controlled at body.

Encoder Sequence for OPB822

Encoder Sequence for OPB826



For information on encoder design, see Application Bulletin 203 at: http://www.optekinc.com/pdf/App_Note_203.pdf



General Note

OPB822S, OPB822SD





Electrical Characteristics (OPB822, OPB826) (T_A = 25°C unless otherwise noted)

YMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
put Diode	e (see OP14O for OPB822 or OP266 for OPB8	326 for ad	lditiona	l informa	tion)	
V_{F}	Forward Voltage	-	-	1.7	V	I _F = 20 mA
I _R	Reverse Current	-	-	100	μΑ	V _R = 2 V
output Pho	stotransistor (see OP550 for OPB822 or OP5	06 for OP	B826 fc	r additio	nal inform	nation)
V _{(BR)(CEO)}	Collector-Emitter Breakdown Voltage	30	-	-	V	I _C = 1 mA
V _{(BR)(ECO)}	Emitter-Collector Breakdown Voltage	5	-	-	V	Ι _Ε = 100 μΑ
I _{CEO}	Collector-Emitter Leakage Current	-	-	100	nA	$V_{CE} = 10 \text{ V}, I_F = 0, E_E = 0$
oupled		•	•			
I _{С(ОN)}	On-State Collector Current OPB822S OPB822SD OPB826S OPB826SD	250 100 250 100		- - -	μΑ μΑ μΑ μΑ	$V_{CE} = 5 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 5 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 10 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 10 \text{ V, } I_F = 20 \text{ mA}$
V _{CE(SAT)}	Collector-Emitter Saturation Voltage OPB822S OPB822SD OPB826S OPB826SD	- - -	- - -	0.4 0.4 0.4 0.4	V V V	I_C = 125 μ A, I_F = 20 mA I_C = 50 μ A, I_F = 20 mA I_C = 125 μ A, I_F = 20 mA I_C = 50 μ A, I_F = 20 mA
I _{CX1}	Crosstalk OPB822D, OPB822SD OPB826S		-	250 20	μА	I _{F1} = 0 mA, I _{F2} = 20 mA, V _{CE} = 10 V

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Notes:

OPB826SD

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⁽¹⁾ All parameters tested using pulse techniques.